

# **2018 IEEE International Conference on Smart Materials and Spectroscopy (SMS 2018)**

**Hammamet, Tunisia  
12-15 October 2018**



**IEEE Catalog Number: CFP18P51-POD  
ISBN: 978-1-5386-7184-9**

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IEEE Catalog Number:	CFP18P51-POD
ISBN (Print-On-Demand):	978-1-5386-7184-9
ISBN (Online):	978-1-5386-7183-2

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